Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2024-07-08
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
Antonella Lanzafame
Date: 2024.07.08
10:12:43 CEST

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSB952IYQ2T	Z7GA	A	#REF!	2024-07-08
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	21.30	mg	Each	ECOPACK® 3
Identity	**Authority**			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), immersion	Copper Alloy	0

Package designator	Package size	Number of instances	Shape	
qfn	3 x 3	8	Flat	
Comment				
Comment	A03Y WDFPN 3x3x0.8 8L P0.65 WET.FLK			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	**Description**

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	**Description**

QueryList : California Prop65 list, dated 29th December 2023			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	**amount in product (mg)**	**Application**	**ppm in product**

QueryList :Customer	**Response**
QUERY	**Response**

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				**Response**
QUERY				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	**Cadmium (Cd)**	**Mercury (Hg)**	**Hexavalent Chromium (Cr VI)**	**PBB & PBDE**
O	O	O	O	O

QueryList : REACH-23rd January 2024				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material

QueryList : Responsible metals sourcing	**Response**
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Gold, Tin, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	**Response**
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	**Response**
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	**Response**
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

QueryList : EUSRR Directive	**Response**
Product contains hazardous materials listed in EUSRR Annex II	False

PFAS/PTFE Declaration	**Response**
QUERY	**Response**
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	**Response**
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	**Response**
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	**Response**
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**Z7GA**		143.0494		#N/A	6715935.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	0.890	mg	supplier	die	Silicon(Si)	7440-21-3		0.789	mg	886517	37042
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.007	mg	7865	329
				supplier	metallisation	Copper(Cu)	7440-50-8		0.063	mg	70787	2958
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	1124	47
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	1124	47
				supplier	passivation	Silicon oxide	7631-86-9		0.029	mg	32584	1362
Leadframe	M-004 Copper and its alloys	34.944	mg	supplier	alloy	Cu	7440-50-8		33.885	mg	5408619	1590845
				supplier	alloy	Si	7440-31-5		0.797	mg	127215	37418
				supplier	alloy	Ni	7440-02-0		0.048	mg	7662	2254
				supplier	alloy	Mg	7439-95-4		0.042	mg	#N/A	1972
				supplier	metallization	Silver (Ag)	7440-22-4		0.172	mg	27454	8075
Die attach	M-011 Other inorganic materials	0.351	mg	supplier	glue	Silver	7440-22-4		0.308	mg	49162	14460
				supplier	glue	Acrylate monomer	61434-04-6		0.018	mg	#N/A	845
				supplier	glue	Acrylate oligomer	Proprietary		0.018	mg	#N/A	845
				supplier	glue	Bismaleimide resin	Proprietary		0.007	mg	#N/A	329
Bonding wires	M-004 Copper and its alloys	0.269	mg	supplier	wire	Cu	7440-50-8		0.269	mg	42937	12629
Encapsulation	M-011 Other inorganic materials	91.192	mg	supplier	mold compound	Epoxy Resin 1	Proprietary		65.293	mg	#N/A	3065399
				supplier	mold compound	Epoxy Resin 2	Proprietary		13.679	mg	#N/A	642207
				supplier	mold compound	Epoxy Resin 3	Proprietary		6.839	mg	#N/A	321080
				supplier	mold compound	Phenol Resin	Proprietary		4.560	mg	#N/A	214085
				supplier	mold compound	Carbon black	1333-86-4		0.456	mg	#N/A	21408
				supplier	mold compound	Amorphous silica	60676-86-0		0.365	mg	#N/A	17136
Connections coating	Solder	1.258	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		1.258	mg	200798	59061
Die attach	M-011 Other inorganic materials	0.137	mg	supplier	glue	Epoxy Resin A	29690-82-2		0.010	mg	70000	449
				supplier	glue	Epoxy Resin B	9003-36-5		0.019	mg	140000	899
				#N/A	glue	Phenol Resin	25085-75-0		0.019	mg	140000	899
				supplier	glue	SiO2 Filler	7631-86-9		0.068	mg	500000	3211
				#N/A	glue	Acrylic Copolymer	58152-79-7		0.021	mg	150000	963
Bonding wires	M-008 Precious metals	0.083	mg	supplier	wire	Gold	7440-57-5		0.082	mg	992000	3856
	0			supplier	wire	Pt	7440-06-4		0.0005	mg	6000	23
	0			supplier	wire	Pd	7440-05-3		0.0002	mg	2000	8
Encapsulation	M-011 Other inorganic materials	12.747	mg	#N/A	mold compound	Epoxy Resin	Trade secret		0.623	mg	48894	29261
				#N/A	mold compound	Phenol Resin	Trade secret		0.337	mg	26403	15801
				supplier	mold compound	Silica (Amorphous)A	60676-86-0		11.127	mg	872876	522383
				supplier	mold compound	Silica (Amorphous)B	7631-86-9		0.623	mg	48894	29261
				supplier	mold compound	Carbon Black	1333-86-4		0.037	mg	2934	1756
Connections coating	Solder	1.179	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.179	mg	1000000	55332